

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10509895			
<b>Filing Date:</b>	01-Oct-2004			
<b>Title of Invention:</b>	Method for severing brittle material substrate and severing apparatus using the method			
<b>First Named Inventor/Applicant Name:</b>	Kazuya Maekawa			
<b>Filer:</b>	Lee Cheng/Conlee Tercenio			
<b>Attorney Docket Number:</b>	APA-0217			
Filed as Small Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Claims in excess of 20	2615	2	26	52
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 1 month with \$0 paid	2251	1	65	65
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>117</b>